

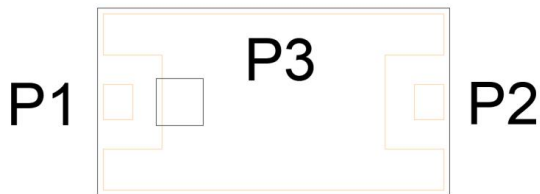
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

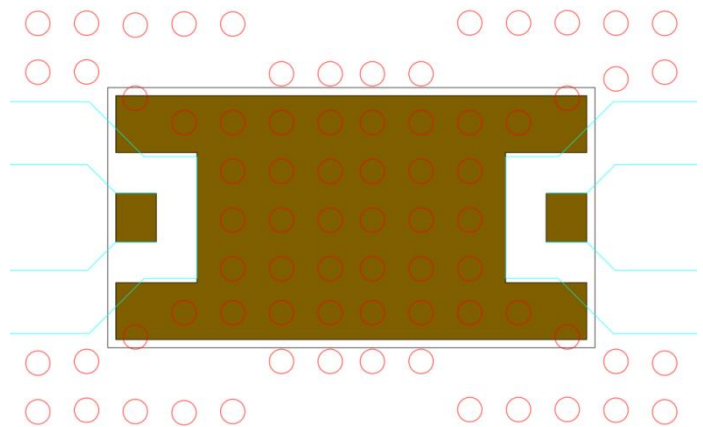
NO.	Parameter	Frequency (MHz)	SPEC		
			Min.	Typ.	Max.
1	Insertion Loss (dB) @25°C	710~790			3.0
2	Ripple in BW (dB)	710~790			1.0
3	VSWR	710~790			1.8
4	Attenuation (dB)	590	40		
		910	40		
5	Phase consistency (°)	$\pm 3^\circ$			

Construction



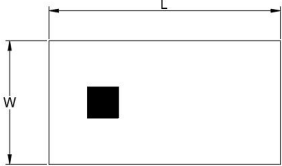
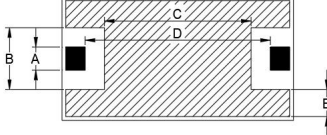
PIN	Connection
1	Input Port
2	Output Port
3	GND

Mounting Considerations

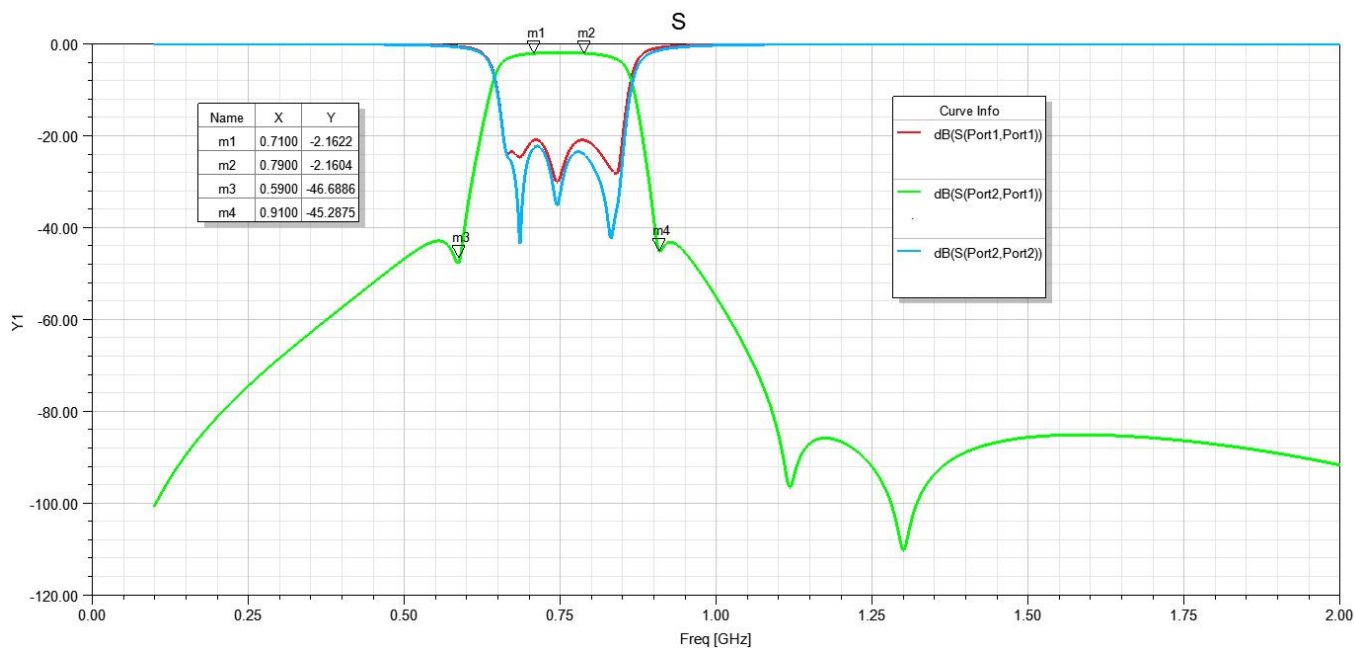


Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

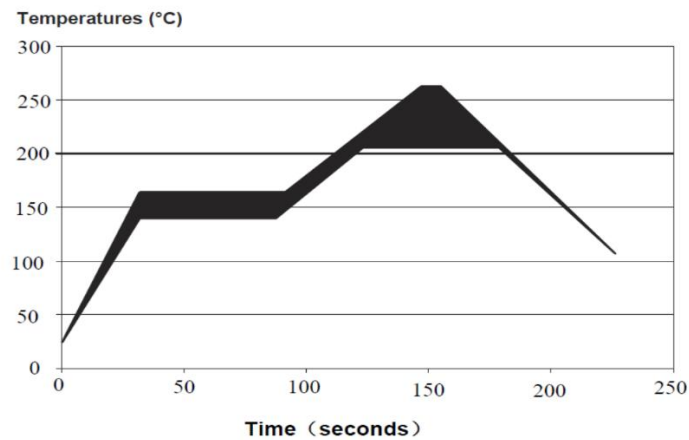
Dimensions

Figure	Symbol	Dimension (mm)
Top View  Side View  Bottom View 	L	6.00 ± 0.20
	W	3.20 ± 0.20
	T	2.00 max.
	A	0.60 ± 0.15
	B	1.60 ± 0.15
	C	3.80 ± 0.15
	D	4.80 ± 0.15
	E	0.70 ± 0.15

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.